



LIST OF REFERENCES CITED BY APPLICANT (Use several sheets if necessary)	ATTY. DOCKET NO.	SERIAL NO.
	7828-003	08/082,328
	APPLICANT	
	Thomas Knight and David Salzman	
	FILING DATE	GROUP
	June 24, 1993	2841

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
BV	AA	4,339,668	7/13/82	Mueller <i>et al.</i>	307	149	
BV	AB	4,654,581	3/31/87	Neukermans <i>et al.</i>	324	0725	
BV	AC	4,931,991	6/5/90	Cvijanovich	365	52	
BV	AD	5,012,321	4/30/91	Magarshack	257	7664	
BV	AE	5,119,172	6/2/92	Cho <i>et al.</i>	257	72684	
	AF						
	AG						

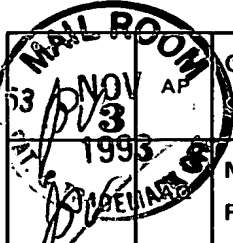
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		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
BV	AH	EP 0 498 298 A1	11/20/92	European Patent Office				
	AI							

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

BV	AJ	Turlik, Iwona, (Ed.), "Prolog to The Special Section on Multichip Module Technology," <i>Proc. IEEE</i> , Vol. 80, No. 12 (Dec. 1992)
BV	AK	Martin <i>et al.</i> , "A Practical Approach to Producing Known-Good Die," <i>ICEMM Proc. '93, International Conference and Exhibition on Multichip Modules</i> , pp. 139-151 (April 1993)
BV	AL	Begay <i>et al.</i> , "Getting to Know Your MCM Die," <i>ICEMM Proc. '93, International Conference and Exhibition on Multichip Modules</i> , pp. 160-165 (April 1993)
BV	AM	Neugebauer, <i>et al.</i> , "Multichip Module Designs for High Performance Applications," <i>Proceedings of NEPCON West</i> (1989), reprinted in <i>MULTICHIP MODULES: SYSTEMS ADVANTAGES, MAJOR CONSTRUCTIONS, AND MATERIALS TECHNOLOGIES</i> , Johnson <i>et al.</i> (Eds.). (1991)
BV	AN	Balde, "Multichip Packaging and the Need for New Materials," <i>Journal of Electronic Materials</i> (Feb. 1989), reprinted in <i>MULTICHIP MODULES: SYSTEMS ADVANTAGES, MAJOR CONSTRUCTIONS, AND MATERIALS TECHNOLOGIES</i> , Johnson <i>et al.</i> (Eds.). (1991)
BV	AO	Doane and Franzon, (Eds.), <i>MCM Technologies and Alternatives, The Basics</i> , pp. 1-35, 37-131, 817-843 (1992)

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Ghappell *et al.*, "Fast CMOS ECL Receivers With 100-mV Worst-Case Sensitivity," *IEEE Journal of Solid-State Circuits*, Vol. 23. No. 1 (Feb. 1988)

Morris, (Ed.), *Electronics Packaging Forum*, Vol. 1, State Univ. of NY, Binghamton, Van Nostrand Reinhold, NY, pp. 1-116 (1990)

EXAMINER

John P. Vignola

DATE CONSIDERED

March 22, 2001

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*Paper No. 8**Paper No. 8*

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<i>pv</i>	AB	Martin <i>et al.</i> , "A Practical Approach to Producing Known-Good Die," <i>ICEMM Proc. '93, International Conference and Exhibition on Multichip Modules</i> , pp. 139-151 (April 1993)
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<i>pv</i>	AE	Balde, "Multichip Packaging and the Need for New Materials," <i>Journal of Electronic Materials</i> (Feb. 1989), <i>reprinted in MULTICHIP MODULES: SYSTEMS ADVANTAGES, MAJOR CONSTRUCTIONS, AND MATERIALS TECHNOLOGIES</i> , Johnson <i>et al.</i> (Eds.) (1991)
<i>pv</i>	AF	Doane and Franzon, (Eds.), <i>MCM Technologies and Alternatives, The Basics</i> , pp. 1-35, 37-131, 817-843 (1992)
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<i>pv</i>	AI	IBM Technical Disclosure Bulletin, Vol. 6, No. 11, April 1964 New York, pp. 43-44 "Modular Read Only Store"
<i>pv</i>	AJ	Knight and Salzman, "Manufacturability of Capacitively Coupled Multichip Modules" 1994 Proceedings 44 th Electronic Components and Technology Conference, May 1994.

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